

AMENDMENTS TO THE CLAIMS

A detailed listing of all claims that are, or were, in the present application, irrespective of whether the claim(s) remains under examination in the application are presented below. The claims are presented in ascending order and each includes one status identifier.

1. (Previously Presented) A sealable wafer carrier for holding semiconductor wafers in a generally horizontal orientation comprising: an enclosure portion and a door, the enclosure portion formed substantially from polycarbonate plastic and including at least a top, a bottom, a pair of opposing sides, a back, an open front defining a door frame for receiving the door, a plurality of wafer supports in said enclosure, said wafer supports presenting a plurality of slots, each slot adapted to receive a semiconductor wafer, and a kinematic coupling on the bottom of the enclosure portion;

the door receivable in the door frame to sealingly close the open front, the door having an exterior surface, an interior surface, and a periphery, the door comprising:

at least one latching mechanism robotically operable from outside the enclosure portion when the door is received in the door frame;

a wafer cushion portion on the interior surface of the door, the wafer cushion portion adapted to engage and cushion the semiconductor wafers when the door is received in the door frame;

wherein the exterior surface of the door comprises a layer formed substantially from a plastic material selected from the group of plastic materials consisting of polyimide, polyether imide, polyamide imide, polyketone, polyetherketone, polyetheretherketone,

polyetherketoneketone, polyether sulphone, and polytetrafluoroethylene, and wherein said layer has a Fire Propagation Index of not greater than $9.0 \text{ (m/s}^{1/2})\text{(kW/m)}^{-2/3}$ so that the outer surface portion is relatively retardant to vertical propagation of fire.

2. (Previously Presented) The wafer carrier of claim 1, wherein the layer of said exterior surface of said door is formed from polyether imide plastic.

3. (Previously Presented) The wafer carrier of claim 1, wherein the layer of said exterior surface of said door is formed from polyetheretherketone plastic.

4. Cancelled.

5. (Previously Presented) The wafer carrier of claim 1, wherein the interior surface of the door comprises polycarbonate plastic.

6. (Previously Presented) The wafer carrier of claim 1, wherein said door of said wafer carrier is made by a process comprising molding the layer of fire retardant plastic over a layer of polycarbonate plastic, so that said fire retardant plastic layer forms the exterior surface of said door.

7. (Previously Presented) The wafer carrier of claim 1, wherein said door of said wafer carrier is made by a process comprising affixing a shield panel made from fire retardant plastic to said door with an adhesive, so that said shield panel forms the exterior surface of said door.

8. (Previously Presented) The wafer carrier of claim 1, wherein door of said wafer carrier is made by a process comprising affixing a shield panel to said door with a plurality of fasteners, so that said shield panel forms the exterior surface of said door.

9-38. Cancelled.